



HMPS8099

NPN SILICON TRANSISTOR

Description

HMPS8099 is designed for general purpose amplifier applications.

Features

- Low Collector-Emitter Saturation Voltage
- HMPS8099 is complementary to HMPS8599



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +125 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage 80 V
 VCES Collector to Emitter Voltage..... 80 V
 VEBO Emitter to Base Voltage 6 V
 IC Collector Current 500 mA

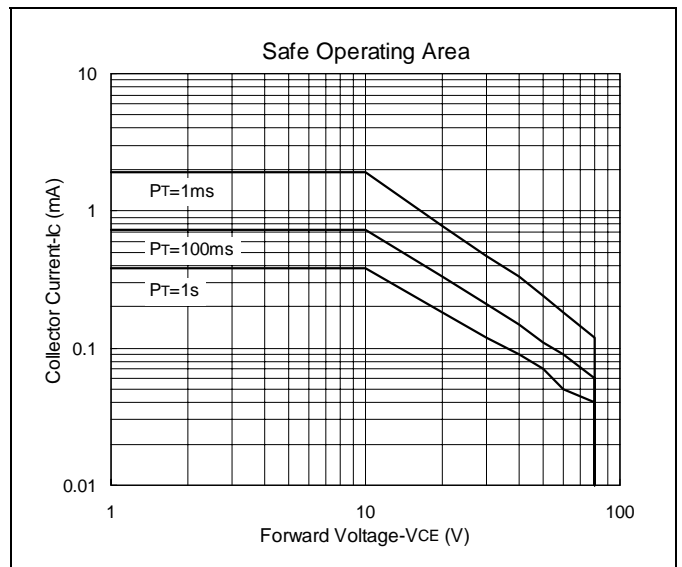
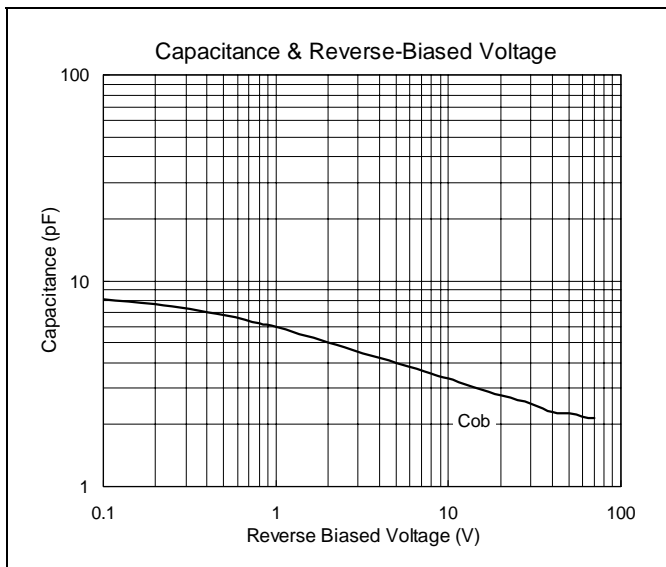
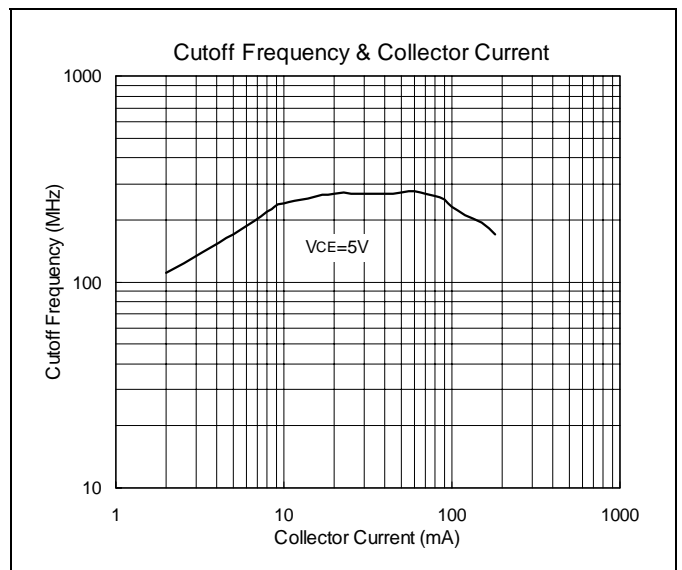
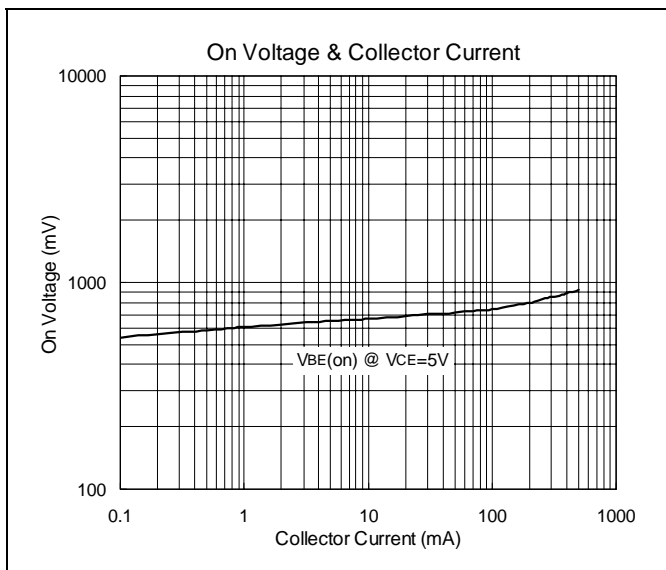
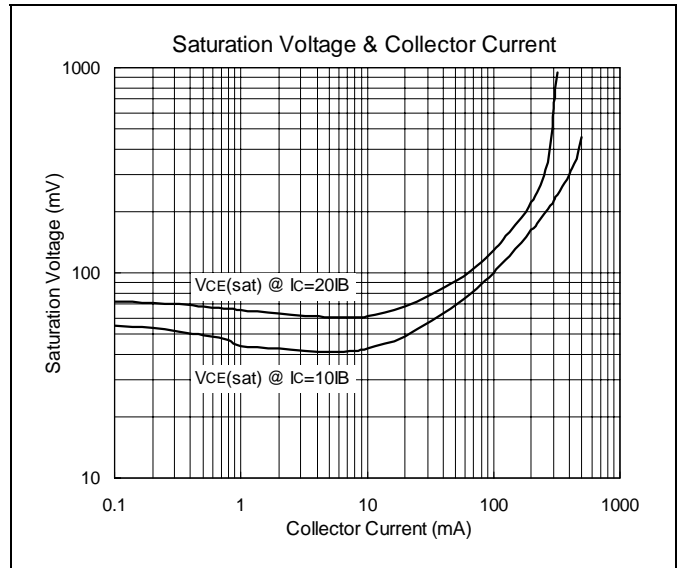
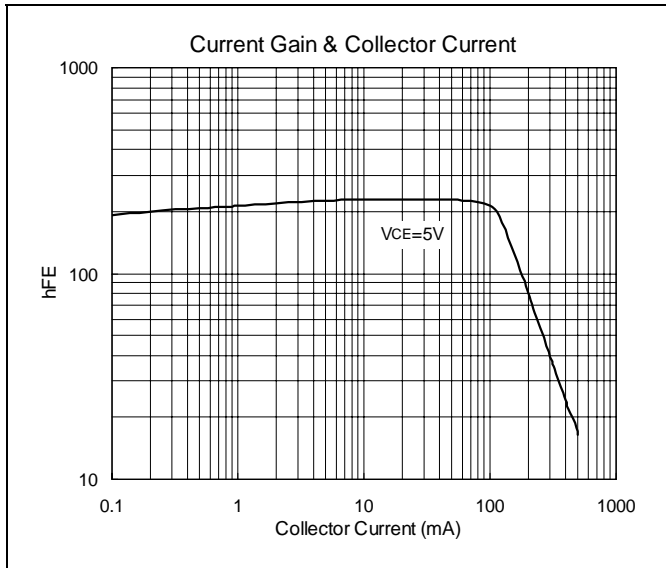
Characteristics (Ta=25°C)

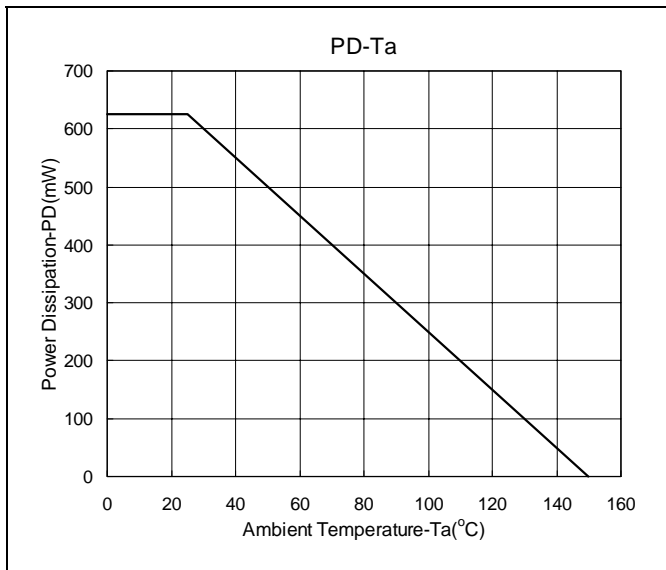
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	80	-	-	V	IC=100uA, IE=0
BVCEO	80	-	-	V	IC=10mA, IB=0
BVEBO	6	-	-	V	IE=10uA, IC=0
ICBO	-	-	100	nA	VCB=80V, IE=0
IEBO	-	-	100	nA	VEB=4V, IC=0
ICEO	-	-	100	nA	VCE=60V, IB=0
*hFE1	100	-	300		IC=1mA, VCE=5V
*hFE2	100	-	-		IC=10mA, VCE=5V
*hFE3	75	-	-		IC=100mA, VCE=5V
*VCE(sat)1	-	-	0.4	V	IC=100mA, IB=5mA
*VCE(sat)2	-	-	0.3	V	IC=100mA, IB=10mA
VBE(on)	0.6	-	0.8	V	IC=10mA, VCE=5V

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



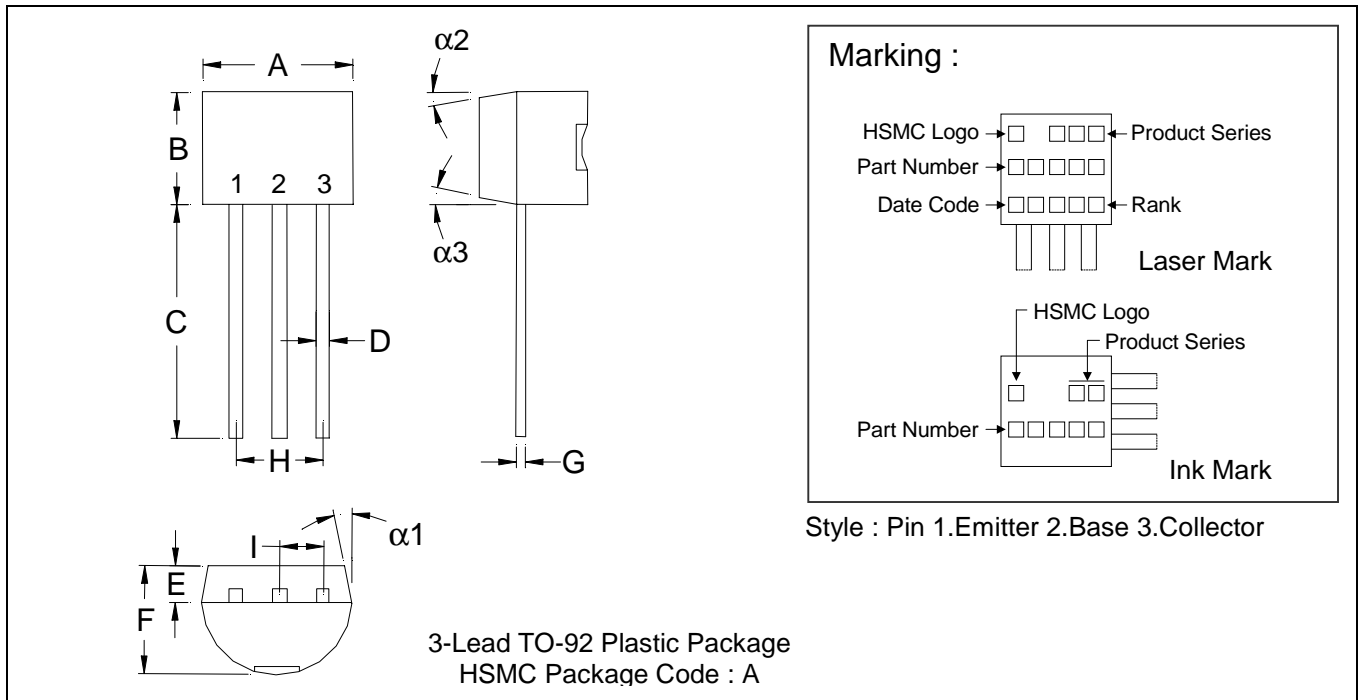
Characteristics Curve







TO-92 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5977061 Fax : 886-3-5979220